



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2400
Number of Logic Elements/Cells	10800
Total RAM Bits	573440
Number of I/O	404
Number of Gates	129600
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv405e-6fg676c

Table 1: Virtex-E Extended Memory Field-Programmable Gate Array Family Members

Device	Logic Gates	CLB Array	Logic Cells	Differential I/O Pairs	User I/O	BlockRAM Bits	Distributed RAM Bits
XCV405E	129,600	40 x 60	10,800	183	404	573,440	153,600
XCV812E	254,016	56 x 84	21,168	201	556	1,146,880	301,056

Virtex-E Compared to Virtex Devices

The Virtex-E family offers up to 43,200 logic cells in devices up to 30% faster than the Virtex family.

I/O performance is increased to 622 Mb/s using Source Synchronous data transmission architectures and synchronous system performance up to 240 MHz using singled-ended SelectI/O technology. Additional I/O standards are supported, notably LVPECL, LVDS, and BLVDS, which use two pins per signal. Almost all signal pins can be used for these new standards.

Virtex-E devices have up to 640 Kb of faster (250MHz) block SelectRAM, but the individual RAMs are the same size and structure as in the Virtex family. They also have eight DLLs instead of the four in Virtex devices. Each individual DLL is slightly improved with easier clock mirroring and 4x frequency multiplication.

V_{CCINT} , the supply voltage for the internal logic and memory, is 1.8 V, instead of 2.5 V for Virtex devices. Advanced processing and 0.18 μ m design rules have resulted in smaller dice, faster speed, and lower power consumption.

I/O pins are 3 V tolerant, and can be 5 V tolerant with an external 100 Ω resistor. PCI 5 V is not supported. With the addition of appropriate external resistors, any pin can tolerate any voltage desired.

Banking rules are different. With Virtex devices, all input buffers are powered by V_{CCINT} . With Virtex-E devices, the LVTTTL, LVCMOS2, and PCI input buffers are powered by the I/O supply voltage V_{CCO} .

The Virtex-E family is not bitstream-compatible with the Virtex family, but Virtex designs can be compiled into equivalent Virtex-E devices.

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions. See the data sheet pinout section for details.

General Description

The Virtex-E FPGA family delivers high-performance, high-capacity programmable logic solutions. Dramatic increases in silicon efficiency result from optimizing the new architecture for place-and-route efficiency and exploiting an aggressive 6-layer metal 0.18 μ m CMOS process. These advances make Virtex-E FPGAs powerful and flexible alter-

natives to mask-programmed gate arrays. The Virtex-E family includes the nine members in Table 1.

Building on experience gained from Virtex FPGAs, the Virtex-E family is an evolutionary step forward in programmable logic design. Combining a wide variety of programmable system features, a rich hierarchy of fast, flexible interconnect resources, and advanced process technology, the Virtex-E family delivers a high-speed and high-capacity programmable logic solution that enhances design flexibility while reducing time-to-market.

Virtex-E Architecture

Virtex-E devices feature a flexible, regular architecture that comprises an array of configurable logic blocks (CLBs) surrounded by programmable input/output blocks (IOBs), all interconnected by a rich hierarchy of fast, versatile routing resources. The abundance of routing resources permits the Virtex-E family to accommodate even the largest and most complex designs.

Virtex-E FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. Configuration data can be read from an external SPROM (master serial mode), or can be written into the FPGA (SelectMAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation Series™ and Alliance Series™ Development systems deliver complete design support for Virtex-E, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation and downloading of a configuration bit stream.

Higher Performance

Virtex-E devices provide better performance than previous generations of FPGAs. Designs can achieve synchronous system clock rates up to 240 MHz including I/O or 622 Mb/s using Source Synchronous data transmission architectures. Virtex-E I/Os comply fully with 3.3 V PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz.

While performance is design-dependent, many designs operate internally at speeds in excess of 133 MHz and can achieve over 311 MHz. Table 2, page 3, shows performance data for representative circuits, using worst-case timing parameters.

Architectural Description

Virtex-E Array

The Virtex-E user-programmable gate array (see [Figure 1](#)) comprises two major configurable elements: configurable logic blocks (CLBs) and input/output blocks (IOBs).

- CLBs provide the functional elements for constructing logic.
- IOBs provide the interface between the package pins and the CLBs.

CLBs interconnect through a general routing matrix (GRM). The GRM comprises an array of routing switches located at the intersections of horizontal and vertical routing channels. Each CLB nests into a VersaBlock™ that also provides local routing resources to connect the CLB to the GRM.

The VersaRing™ I/O interface provides additional routing resources around the periphery of the device. This routing improves I/O routability and facilitates pin locking.

The Virtex-E architecture also includes the following circuits that connect to the GRM:

- Dedicated block memories of 4096 bits each
- Clock DLLs for clock-distribution delay compensation and clock domain control
- 3-State buffers (BUFTs) associated with each CLB that drive dedicated segmentable horizontal routing resources

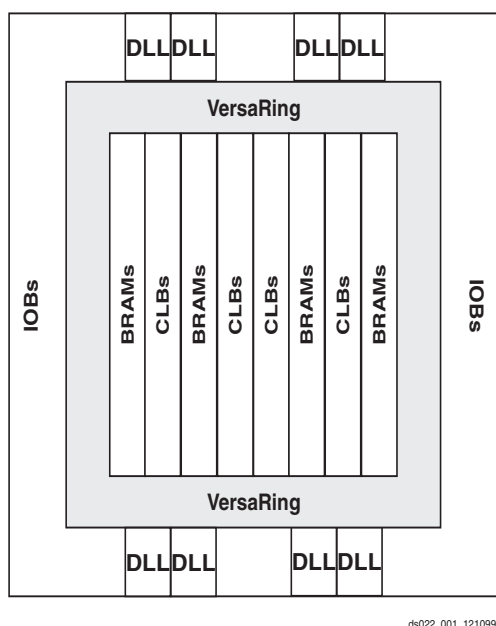


Figure 1: Virtex-E Architecture Overview

Values stored in static memory cells control the configurable logic elements and interconnect resources. These values load into the memory cells on power-up, and can reload if necessary to change the function of the device.

Input/Output Block

The Virtex-E IOB, [Figure 2](#), features SelectIO+™ inputs and outputs that support a wide variety of I/O signalling standards (see [Table 1](#)).

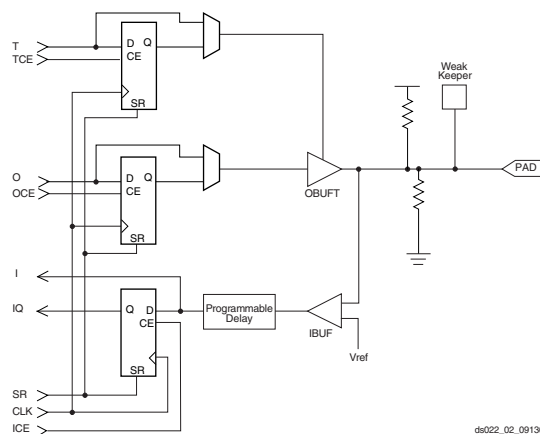
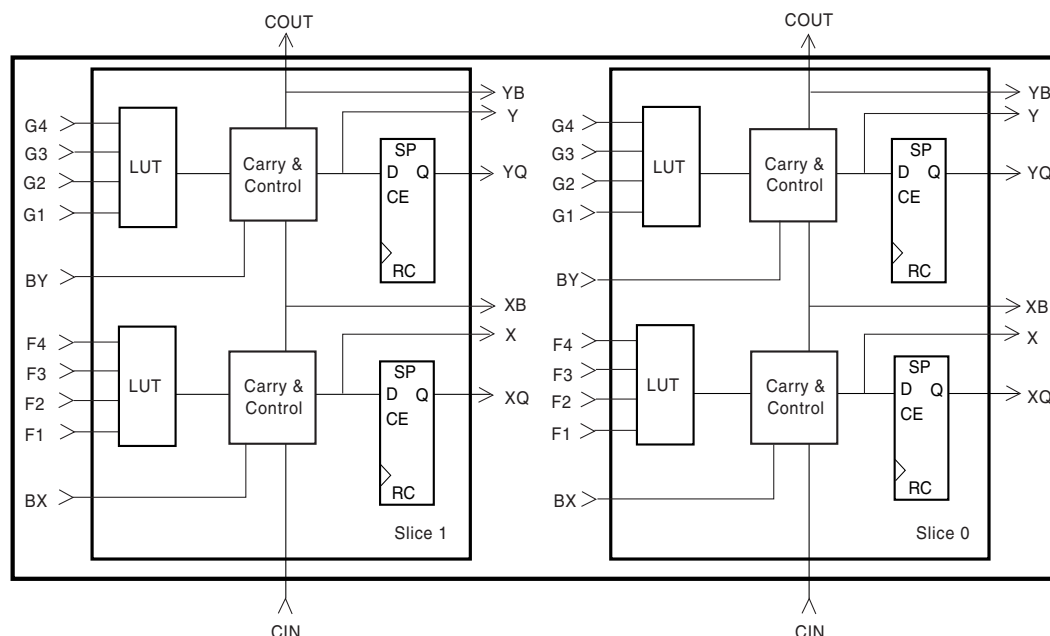


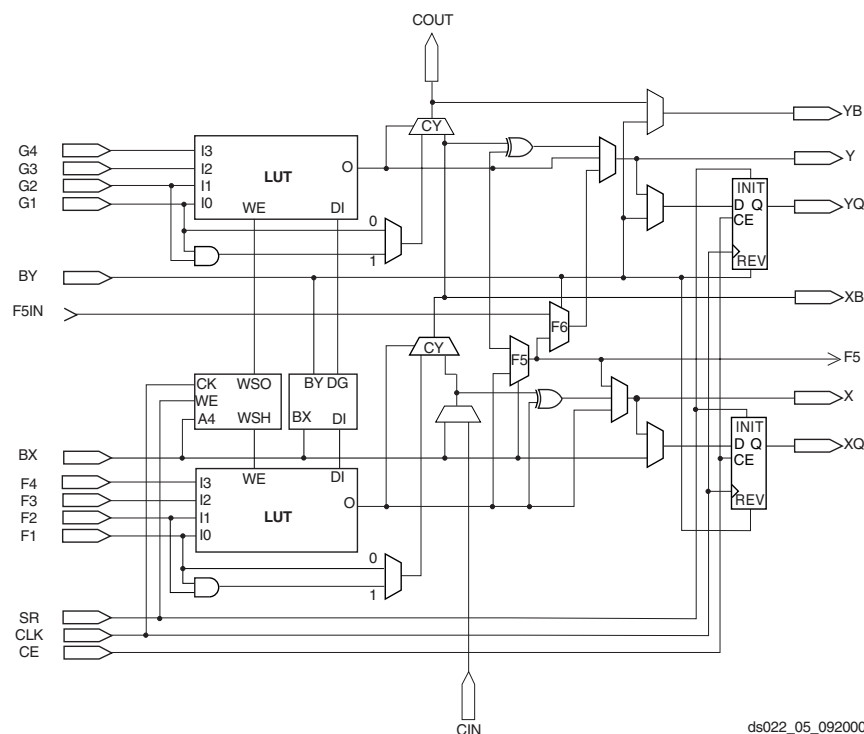
Figure 2: Virtex-E Input/Output Block (IOB)

The three IOB storage elements function either as edge-triggered D-type flip-flops or as level-sensitive latches. Each IOB has a clock signal (CLK) shared by the three flip-flops and independent clock enable signals for each flip-flop.



ds022_04_121799

Figure 4: 2-Slice Virtex-E CLB



ds022_05_092000

Figure 5: Detailed View of Virtex-E Slice

In addition to the four basic LCs, the Virtex-E CLB contains logic that combines function generators to provide functions of five or six inputs. Consequently, when estimating the number of system gates provided by a given device, each CLB counts as 4.5 LCs.

Look-Up Tables

Virtex-E function generators are implemented as 4-input look-up tables (LUTs). In addition to operating as a function generator, each LUT can provide a 16 x 1-bit synchronous RAM. Furthermore, the two LUTs within a slice can be com-

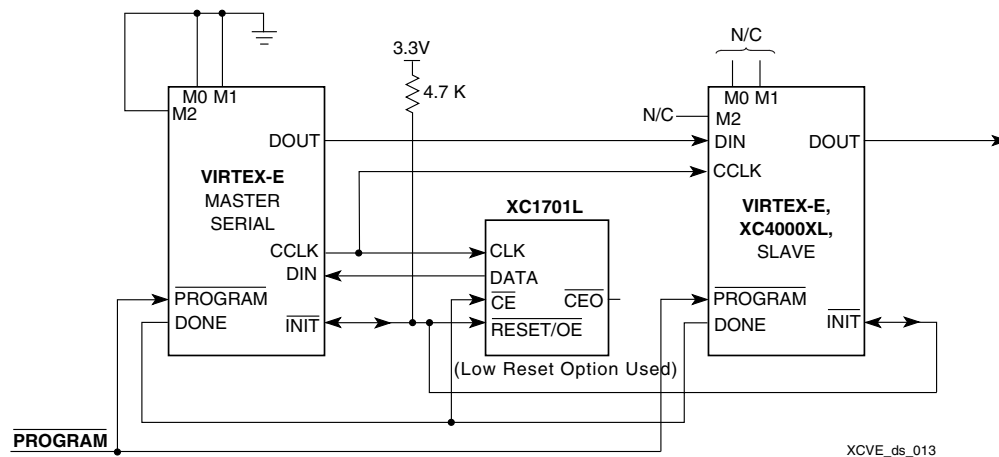


Figure 13: Master/Slave Serial Mode Circuit Diagram

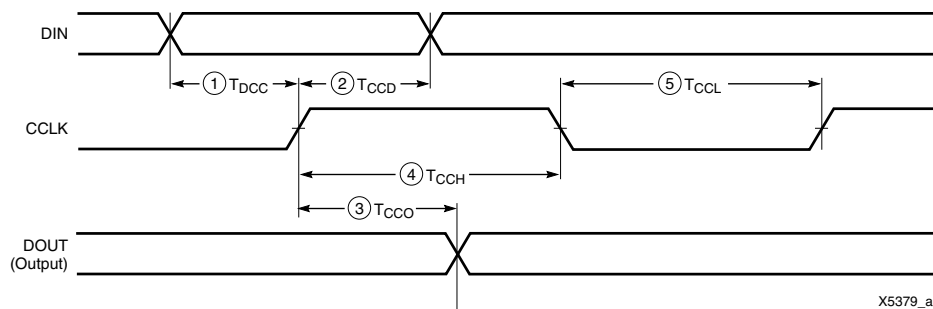


Figure 14: Slave-Serial Mode Programming Switching Characteristics

Master-Serial Mode

In master-serial mode, the CCLK output of the FPGA drives a Xilinx Serial PROM that feeds bit-serial data to the DIN input. The FPGA accepts this data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the rising CCLK edge.

The interface is identical to slave-serial except that an internal oscillator is used to generate the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK which always starts at a slow default frequency. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration. Switching to a lower frequency is prohibited.

The CCLK frequency is set using the ConfigRate option in the bitstream generation software. The maximum CCLK fre-

quency that can be selected is 60 MHz. When selecting a CCLK frequency, ensure that the serial PROM and any daisy-chained FPGAs are fast enough to support the clock rate.

On power-up, the CCLK frequency is approximately 2.5 MHz. This frequency is used until the ConfigRate bits have been loaded when the frequency changes to the selected ConfigRate. Unless a different frequency is specified in the design, the default ConfigRate is 4 MHz.

Figure 13 shows a full master/slave system. In this system, the left-most device operates in master-serial mode. The remaining devices operate in slave-serial mode. The SPROM RESET pin is driven by INIT, and the CE input is driven by DONE. There is the potential for contention on the DONE pin, depending on the start-up sequence options chosen.

Port Signals

Each block SelectRAM+ port operates independently of the others while accessing the same set of 4096 memory cells.

Table 15 describes the depth and width aspect ratios for the block SelectRAM+ memory.

Table 15: Block SelectRAM+ Port Aspect Ratios

Width	Depth	ADDR Bus	Data Bus
1	4096	ADDR<11:0>	DATA<0>
2	2048	ADDR<10:0>	DATA<1:0>
4	1024	ADDR<9:0>	DATA<3:0>
8	512	ADDR<8:0>	DATA<7:0>
16	256	ADDR<7:0>	DATA<15:0>

Clock—CLK[AIB]

Each port is fully synchronous with independent clock pins. All port input pins have setup time referenced to the port CLK pin. The data output bus has a clock-to-out time referenced to the CLK pin.

Enable—EN[AIB]

The enable pin affects the read, write and reset functionality of the port. Ports with an inactive enable pin keep the output pins in the previous state and do not write data to the memory cells.

Write Enable—WE[AIB]

Activating the write enable pin allows the port to write to the memory cells. When active, the contents of the data input bus are written to the RAM at the address pointed to by the address bus, and the new data also reflects on the data out bus. When inactive, a read operation occurs and the contents of the memory cells referenced by the address bus reflect on the data out bus.

Reset—RST[AIB]

The reset pin forces the data output bus latches to zero synchronously. This does not affect the memory cells of the RAM and does not disturb a write operation on the other port.

Address Bus—ADDR[AIB]<#:0>

The address bus selects the memory cells for read or write. The width of the port determines the required width of this bus as shown in **Table 15**.

Data In Bus—DI[AIB]<#:0>

The data in bus provides the new data value to be written into the RAM. This bus and the port have the same width, as shown in **Table 15**.

Data Output Bus—DO[AIB]<#:0>

The data out bus reflects the contents of the memory cells referenced by the address bus at the last active clock edge. During a write operation, the data out bus reflects the data in bus. The width of this bus equals the width of the port. The allowed widths appear in **Table 15**.

Inverting Control Pins

The four control pins (CLK, EN, WE and RST) for each port have independent inversion control as a configuration option.

Address Mapping

Each port accesses the same set of 4096 memory cells using an addressing scheme dependent on the width of the port. The physical RAM location addressed for a particular width are described in the following formula (of interest only when the two ports use different aspect ratios).

$$\text{Start} = ((\text{ADDR}_{\text{port}} + 1) * \text{Width}_{\text{port}}) - 1$$

$$\text{End} = \text{ADDR}_{\text{port}} * \text{Width}_{\text{port}}$$

Table 16 shows low order address mapping for each port width.

Table 16: Port Address Mapping

Port Width	Port Addresses																
1	4095...	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
2	2047...	07	06	05	04	03	02	01	00								
4	1023...	03		02		01		00									
8	511...	01				00											
16	255...	00															

Creating Larger RAM Structures

The block SelectRAM+ columns have specialized routing to allow cascading blocks together with minimal routing delays. This achieves wider or deeper RAM structures with a smaller timing penalty than when using normal routing channels.

Location Constraints

Block SelectRAM+ instances can have LOC properties attached to them to constrain the placement. The block SelectRAM+ placement locations are separate from the CLB location naming convention, allowing the LOC properties to transfer easily from array to array.

The LOC properties use the following form.

$$\text{LOC} = \text{RAMB4_R\#C\#}$$

RAMB4_R0C0 is the upper left RAMB4 location on the device.

Fundamentals

Modern bus applications, pioneered by the largest and most influential companies in the digital electronics industry, are commonly introduced with a new I/O standard tailored specifically to the needs of that application. The bus I/O standards provide specifications to other vendors who create products designed to interface with these applications. Each standard often has its own specifications for current, voltage, I/O buffering, and termination techniques.

The ability to provide the flexibility and time-to-market advantages of programmable logic is increasingly dependent on the capability of the programmable logic device to support an ever increasing variety of I/O standards

The SelectI/O resources feature highly configurable input and output buffers which provide support for a wide variety of I/O standards. As shown in [Table 18](#), each buffer type can support a variety of voltage requirements.

Table 18: Virtex-E Supported I/O Standards

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTTL	3.3	3.3	N/A	N/A
LVC MOS2	2.5	2.5	N/A	N/A
LVC MOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

Overview of Supported I/O Standards

This section provides a brief overview of the I/O standards supported by all Virtex-E devices.

While most I/O standards specify a range of allowed voltages, this document records typical voltage values only. Detailed information on each specification can be found on the Electronic Industry Alliance Jedec website at:

<http://www.jedec.org>

LVTTTL — Low-Voltage TTL

The Low-Voltage TTL, or LVTTTL standard is a general purpose EIA/JESDSA standard for 3.3 V applications that uses an LVTTTL input buffer and a Push-Pull output buffer. This standard requires a 3.3 V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a termination voltage (V_{TT}).

LVC MOS2 — Low-Voltage CMOS for 2.5 Volts

The Low-Voltage CMOS for 2.5 Volts or lower, or LVC MOS2 standard is an extension of the LVC MOS standard (JESD 8-5) used for general purpose 2.5 V applications. This standard requires a 2.5 V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}).

LVC MOS18 — 1.8 V Low Voltage CMOS

This standard is an extension of the LVC MOS standard. It is used in general purpose 1.8 V applications. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required.

PCI — Peripheral Component Interface

The Peripheral Component Interface, or PCI standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses a LVTTTL input buffer and a Push-Pull output buffer. This standard does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}), however, it does require a 3.3 V output source voltage (V_{CCO}).

GTL — Gunning Transceiver Logic Terminated

The Gunning Transceiver Logic, or GTL standard is a high-speed bus standard (JESD8.3) invented by Xerox. Xilinx has implemented the terminated variation for this standard. This standard requires a differential amplifier input buffer and a Open Drain output buffer.

GTL+ — Gunning Transceiver Logic Plus

The Gunning Transceiver Logic Plus, or GTL+ standard is a high-speed bus standard (JESD8.3) first used by the Pentium Pro processor.

HSTL — High-Speed Transceiver Logic

The High-Speed Transceiver Logic, or HSTL standard is a general purpose high-speed, 1.5 V bus standard sponsored by IBM (EIA/JESD 8-6). This standard has four variations or classes. SelectI/O devices support Class I, III, and IV. This

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See [Figure 38](#) for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUF placement restrictions require that any differential amplifier input signals within a bank be of the same standard. How to specify a specific location for the IBUF via the LOC property is described below. [Table 19](#) summarizes the Virtex-E input standards compatibility requirements.

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element by default activates to ensure a zero hold-time requirement. The NODELAY=TRUE property overrides this default.

When the IBUF does not drive a flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

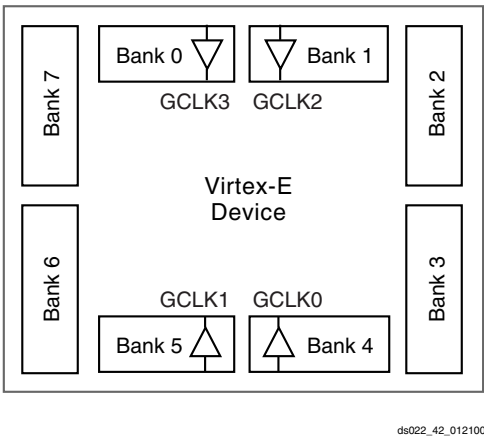


Figure 38: Virtex-E I/O Banks

Table 19: Xilinx Input Standards Compatibility Requirements

Rule 1	Standards with the same input V_{CCO} , output V_{CCO} , and V_{REF} can be placed within the same bank.
--------	--

IBUFG

Signals used as high fanout clock inputs to the Virtex-E device should drive a global clock input buffer (IBUFG) via an external input port in order to take advantage of one of the four dedicated global clock distribution networks. The output of the IBUFG should only drive a CLKDLL,

CLKDLLHF, or a BUFG symbol. The generic Virtex-E IBUFG symbol appears in [Figure 39](#).

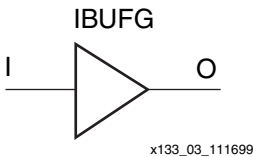


Figure 39: Virtex-E Global Clock Input Buffer (IBUFG) Symbol

The extension to the base name determines which I/O standard is used by the IBUFG. With no extension specified for the generic IBUFG symbol, the assumed standard is LVTTTL.

The following list details variations of the IBUFG symbol.

- IBUFG
- IBUFG_LVCMOS2
- IBUFG_PCI33_3
- IBUFG_PCI66_3
- IBUFG_GTL
- IBUFG_GTLP
- IBUFG_HSTL_I
- IBUFG_HSTL_III
- IBUFG_HSTL_IV
- IBUFG_SSTL3_I
- IBUFG_SSTL3_II
- IBUFG_SSTL2_I
- IBUFG_SSTL2_II
- IBUFG_CTT
- IBUFG_AGP
- IBUFG_LVCMOS18
- IBUFG_LVDS
- IBUFG_LVPECL

When the IBUFG symbol supports an I/O standard that requires a differential amplifier input, the IBUFG automatically configures as a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See [Figure 38](#) for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUFG placement restrictions require any differential amplifier input signals within a bank be of the same standard. The LOC property can specify a location for the IBUFG.

Input termination techniques include the following:

- None
- Parallel (Shunt)

These termination techniques can be applied in any combination. A generic example of each combination of termination methods appears in **Figure 43**.

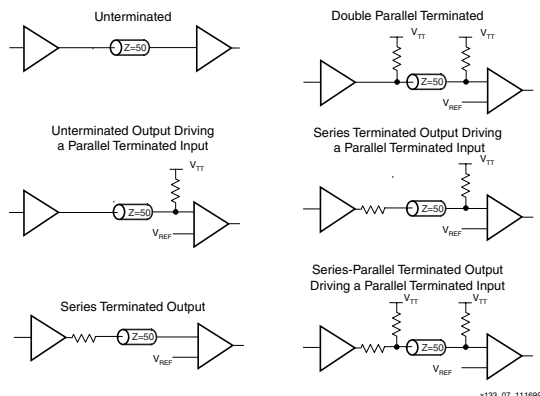


Figure 43: Overview of Standard Input and Output Termination Methods

Simultaneous Switching Guidelines

Ground bounce can occur with high-speed digital ICs when multiple outputs change states simultaneously, causing undesired transient behavior on an output, or in the internal logic. This problem is also referred to as the Simultaneous Switching Output (SSO) problem.

Ground bounce is primarily due to current changes in the combined inductance of ground pins, bond wires, and ground metallization. The IC internal ground level deviates from the external system ground level for a short duration (a few nanoseconds) after multiple outputs change state simultaneously.

Ground bounce affects stable Low outputs and all inputs because they interpret the incoming signal by comparing it to the internal ground. If the ground bounce amplitude exceeds the actual instantaneous noise margin, then a non-changing input can be interpreted as a short pulse with a polarity opposite to the ground bounce.

Table 21 provides the guidelines for the maximum number of simultaneously switching outputs allowed per output power/ground pair to avoid the effects of ground bounce. Refer to **Table 22** for the number of effective output power/ground pairs for each Virtex-E device and package combination.

Table 21: Guidelines for Maximum Number of Simultaneously Switching Outputs per Power/Ground Pair

Standard	Package
	BGA, FGA
LVTTL Slow Slew Rate, 2 mA drive	68
LVTTL Slow Slew Rate, 4 mA drive	41
LVTTL Slow Slew Rate, 6 mA drive	29
LVTTL Slow Slew Rate, 8 mA drive	22
LVTTL Slow Slew Rate, 12 mA drive	17
LVTTL Slow Slew Rate, 16 mA drive	14
LVTTL Slow Slew Rate, 24 mA drive	9
LVTTL Fast Slew Rate, 2 mA drive	40
LVTTL Fast Slew Rate, 4 mA drive	24
LVTTL Fast Slew Rate, 6 mA drive	17
LVTTL Fast Slew Rate, 8 mA drive	13
LVTTL Fast Slew Rate, 12 mA drive	10
LVTTL Fast Slew Rate, 16 mA drive	8
LVTTL Fast Slew Rate, 24 mA drive	5
LVC MOS	10
PCI	8
GTL	4
GTL+	4
HSTL Class I	18
HSTL Class III	9
HSTL Class IV	5
SSTL2 Class I	15
SSTL2 Class II	10
SSTL3 Class I	11
SSTL3 Class II	7
CTT	14
AGP	9

Note: This analysis assumes a 35 pF load for each output.

Table 22: Virtex-E Extended Memory Family Equivalent Power/Ground Pairs

Pkg/Part	XCV405E	XCV812E
BG560		56
FG676	56	
FG900		

LVTTL

LVTTL requires no termination. DC voltage specifications appear in [Table 34](#).

Table 34: LVTTL Voltage Specifications

Parameter	Min	Typ	Max
V _{CCO}	3.0	3.3	3.6
V _{REF}	-	-	-
V _{TT}	-	-	-
V _{IH}	2.0	-	3.6
V _{IL}	-0.5	-	0.8
V _{OH}	2.4	-	-
V _{OL}	-	-	0.4
I _{OH} at V _{OH} (mA)	-24	-	-
I _{OL} at V _{OL} (mA)	24	-	-

Note: V_{OL} and V_{OH} for lower drive currents sample tested.

LVC MOS2

LVC MOS2 requires no termination. DC voltage specifications appear in [Table 35](#).

Table 35: LVC MOS2 Voltage Specifications

Parameter	Min	Typ	Max
V _{CCO}	2.3	2.5	2.7
V _{REF}	-	-	-
V _{TT}	-	-	-
V _{IH}	1.7	-	3.6
V _{IL}	-0.5	-	0.7
V _{OH}	1.9	-	-
V _{OL}	-	-	0.4
I _{OH} at V _{OH} (mA)	-12	-	-
I _{OL} at V _{OL} (mA)	12	-	-

LVC MOS18

LVC MOS18 does not require termination. [Table 36](#) lists DC voltage specifications.

Table 36: LVC MOS18 Voltage Specifications

Parameter	Min	Typ	Max
V _{CCO}	1.70	1.80	1.90
V _{REF}	-	-	-
V _{TT}	-	-	-
V _{IH}	0.65 x V _{CCO}	-	1.95
V _{IL}	-0.5	-	0.2 x V _{CCO}
V _{OH}	V _{CCO} - 0.4	-	-
V _{OL}	-	-	0.4
I _{OH} at V _{OH} (mA)	-8	-	-
I _{OL} at V _{OL} (mA)	8	-	-

AGP-2X

The specification for the AGP-2X standard does not document a recommended termination technique. DC voltage specifications appear in [Table 37](#).

Table 37: AGP-2X Voltage Specifications

Parameter	Min	Typ	Max
V _{CCO}	3.0	3.3	3.6
V _{REF} = N x V _{CCO} ⁽¹⁾	1.17	1.32	1.48
V _{TT}	-	-	-
V _{IH} = V _{REF} + 0.2	1.37	1.52	-
V _{IL} = V _{REF} - 0.2	-	1.12	1.28
V _{OH} = 0.9 x V _{CCO}	2.7	3.0	-
V _{OL} = 0.1 x V _{CCO}	-	0.33	0.36
I _{OH} at V _{OH} (mA)	Note 2	-	-
I _{OL} at V _{OL} (mA)	Note 2	-	-

Notes:

1. N must be greater than or equal to 0.39 and less than or equal to 0.41.
2. Tested according to the relevant specification.

IOB Input Switching Characteristics Standard Adjustments

			Speed Grade ⁽¹⁾				Units
Description	Symbol	Standard	Min	-8	-7	-6	
Data Input Delay Adjustments							
Standard-specific data input delay adjustments	T _{ILVTTL}	LVTTTL	0.0	0.0	0.0	0.0	ns
	T _{ILVCMOS2}	LVC MOS2	−0.02	0.0	0.0	0.0	ns
	T _{ILVCMOS18}	LVC MOS18	−0.02	+0.20	+0.20	+0.20	ns
	T _{ILVDS}	LVDS	0.00	+0.15	+0.15	+0.15	ns
	T _{ILVPECL}	LVPECL	0.00	+0.15	+0.15	+0.15	ns
	T _{IPCI33_3}	PCI, 33 MHz, 3.3 V	−0.05	+0.08	+0.08	+0.08	ns
	T _{IPCI66_3}	PCI, 66 MHz, 3.3 V	−0.05	−0.11	−0.11	−0.11	ns
	T _{IGTL}	GTL	+0.10	+0.14	+0.14	+0.14	ns
	T _{IGTLPLUS}	GTL+	+0.06	+0.14	+0.14	+0.14	ns
	T _{IHSTL}	HSTL	+0.02	+0.04	+0.04	+0.04	ns
	T _{ISSTL2}	SSTL2	−0.04	+0.04	+0.04	+0.04	ns
	T _{ISSTL3}	SSTL3	−0.02	+0.04	+0.04	+0.04	ns
	T _{ICTT}	CTT	+0.01	+0.10	+0.10	+0.10	ns
	T _{IAGP}	AGP	−0.03	+0.04	+0.04	+0.04	ns

Notes:

- Input timing t_i for LVTTTL is measured at 1.4 V. For other I/O standards, see [Table 3](#).

I

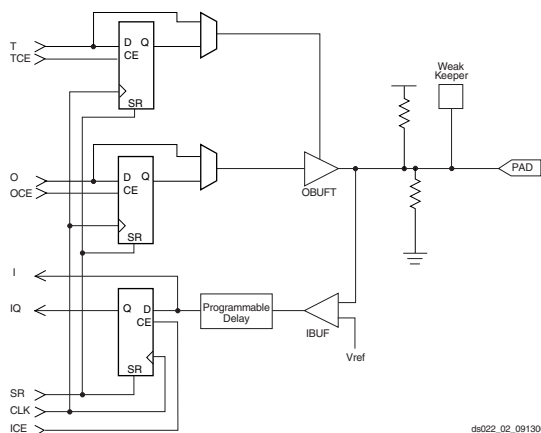


Figure 1: Virtex-E Input/Output Block (IOB)

IOB Output Switching Characteristics, Figure 1

Output delays terminating at a pad are specified for LVTTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays with the values shown in “IOB Output Switching Characteristics Standard Adjustments” on page 8..

		Speed Grade ⁽²⁾				Units
Description ⁽¹⁾	Symbol	Min ³	-8	-7	-6	
Propagation Delays						
O input to Pad	T _{ILOOP}	1.04	2.5	2.7	2.9	ns, max
O input to Pad via transparent latch	T _{IOOLP}	1.24	2.9	3.1	3.4	ns, max
3-State Delays						
T input to Pad high-impedance (Note 2)	T _{IOTHZ}	0.73	1.5	1.7	1.9	ns, max
T input to valid data on Pad	T _{IOTON}	1.13	2.7	2.9	3.1	ns, max
T input to Pad high-impedance via transparent latch (Note 2)	T _{IOTLPHZ}	0.86	1.8	2.0	2.2	ns, max
T input to valid data on Pad via transparent latch	T _{IOTLPON}	1.26	3.0	3.2	3.4	ns, max
GTS to Pad high impedance (Note 2)	T _{GTS}	1.94	4.1	4.6	4.9	ns, max
Sequential Delays						
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T _{CL}	0.56	1.2	1.3	1.4	ns, min
Clock CLK to Pad	T _{IOCKP}	0.97	2.4	2.8	2.9	ns, max
Clock CLK to Pad high-impedance (synchronous) (Note 2)	T _{IOCKHZ}	0.77	1.6	2.0	2.2	ns, max
Clock CLK to valid data on Pad (synchronous)	T _{IOCKON}	1.17	2.8	3.2	3.4	ns, max
Setup and Hold Times before/after Clock CLK						
O input	T _{IOOCK} / T _{IOCKO}	0.43 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
OCE input	T _{IOOCECK} / T _{IOCKOCE}	0.28 / 0	0.55 / 0.01	0.7 / 0	0.7 / 0	ns, min
SR input (OFF)	T _{IOSRCKO} / T _{IOCKOSR}	0.40 / 0	0.8 / 0	0.9 / 0	1.0 / 0	ns, min
3-State Setup Times, T input	T _{IOTCK} / T _{IOCKT}	0.26 / 0	0.51 / 0	0.6 / 0	0.7 / 0	ns, min
3-State Setup Times, TCE input	T _{IOTCECK} / T _{IOCKTCE}	0.30 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
3-State Setup Times, SR input (TFF)	T _{IOSRCKT} / T _{IOCKTSR}	0.38 / 0	0.8 / 0	0.9 / 0	1.0 / 0	ns, min
Set/Reset Delays						
SR input to Pad (asynchronous)	T _{IOSRP}	1.30	3.1	3.3	3.5	ns, max
SR input to Pad high-impedance (asynchronous) (Note 2)	T _{IOSRHZ}	1.08	2.2	2.4	2.7	ns, max
SR input to valid data on Pad (asynchronous)	T _{IOSRON}	1.48	3.4	3.7	3.9	ns, max
GSR to Pad	T _{IOGSRQ}	3.88	7.6	8.5	9.7	ns, max

Notes:

1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.
2. 3-state turn-off delays should not be adjusted.

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used, see [Figure 2](#). The values listed below are worst-case. Precise values are provided by the timing analyzer.

Description ⁽¹⁾	Symbol	Speed Grade				Units
		Min	-8	-7	-6	
Combinatorial Delays						
4-input function: F/G inputs to X/Y outputs	T _{ILO}	0.19	0.40	0.42	0.47	ns, max
5-input function: F/G inputs to F5 output	T _{IF5}	0.36	0.76	0.8	0.9	ns, max
5-input function: F/G inputs to X output	T _{IF5X}	0.35	0.74	0.8	0.9	ns, max
6-input function: F/G inputs to Y output via F6 MUX	T _{IF6Y}	0.35	0.74	0.9	1.0	ns, max
6-input function: F5IN input to Y output	T _{F5INY}	0.04	0.11	0.20	0.22	ns, max
Incremental delay routing through transparent latch to XQ/YQ outputs	T _{IFNCTL}	0.27	0.63	0.7	0.8	ns, max
BY input to YB output	T _{BYYB}	0.19	0.38	0.46	0.51	ns, max
Sequential Delays						
FF Clock CLK to XQ/YQ outputs	T _{CKO}	0.34	0.78	0.9	1.0	ns, max
Latch Clock CLK to XQ/YQ outputs	T _{CKLO}	0.40	0.77	0.9	1.0	ns, max
Setup and Hold Times before/after Clock CLK						
4-input function: F/G Inputs	T _{ICK} / T _{CKI}	0.39 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
5-input function: F/G inputs	T _{IF5CK} / T _{CKIF5}	0.55 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
6-input function: F5IN input	T _{F5INCK} / T _{CKF5IN}	0.27 / 0	0.6 / 0	0.8 / 0	0.8 / 0	ns, min
6-input function: F/G inputs via F6 MUX	T _{IF6CK} / T _{CKIF6}	0.58 / 0	1.3 / 0	1.5 / 0	1.6 / 0	ns, min
BX/BY inputs	T _{DICK} / T _{CKDI}	0.25 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
CE input	T _{CECK} / T _{CKCE}	0.28 / 0	0.55 / 0	0.7 / 0	0.7 / 0	ns, min
SR/BY inputs (synchronous)	T _{RCK} / T _{CKR}	0.24 / 0	0.46 / 0	0.52 / 0	0.6 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T _{CL}	0.56	1.2	1.3	1.4	ns, min
Set/Reset						
Minimum Pulse Width, SR/BY inputs	T _{RPW}	0.94	1.9	2.1	2.4	ns, min
Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	T _{RQ}	0.39	0.8	0.9	1.0	ns, max
Toggle Frequency (MHz) (for export control)	F _{TOG}	-	416	400	357	MHz

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

CLB Arithmetic Switching Characteristics

Setup times not listed explicitly can be approximated by decreasing the combinatorial delays by the setup time adjustment listed. Precise values are provided by the timing analyzer.

Description ⁽¹⁾	Symbol	Speed Grade				Units
		Min	-8	-7	-6	
Combinatorial Delays						
F operand inputs to X via XOR	T _{OPX}	0.32	0.68	0.8	0.8	ns, max
F operand input to XB output	T _{OPXB}	0.35	0.65	0.8	0.9	ns, max
F operand input to Y via XOR	T _{OPY}	0.59	1.07	1.4	1.5	ns, max
F operand input to YB output	T _{OPYB}	0.48	0.89	1.1	1.3	ns, max
F operand input to COUT output	T _{OPCYF}	0.37	0.71	0.9	1.0	ns, max
G operand inputs to Y via XOR	T _{OPGY}	0.34	0.72	0.8	0.9	ns, max
G operand input to YB output	T _{OPGYB}	0.47	0.78	1.2	1.3	ns, max
G operand input to COUT output	T _{OPCYG}	0.36	0.60	0.9	1.0	ns, max
BX initialization input to COUT	T _{BXCY}	0.19	0.36	0.51	0.57	ns, max
CIN input to X output via XOR	T _{CINX}	0.27	0.50	0.6	0.7	ns, max
CIN input to XB	T _{CINXB}	0.02	0.04	0.07	0.08	ns, max
CIN input to Y via XOR	T _{CINY}	0.26	0.45	0.7	0.7	ns, max
CIN input to YB	T _{CINYB}	0.16	0.28	0.38	0.43	ns, max
CIN input to COUT output	T _{BYP}	0.05	0.10	0.14	0.15	ns, max
Multiplier Operation						
F1/2 operand inputs to XB output via AND	T _{FANDXB}	0.10	0.30	0.35	0.39	ns, max
F1/2 operand inputs to YB output via AND	T _{FANDYB}	0.28	0.56	0.7	0.8	ns, max
F1/2 operand inputs to COUT output via AND	T _{FANDCY}	0.17	0.38	0.46	0.51	ns, max
G1/2 operand inputs to YB output via AND	T _{GANDYB}	0.20	0.46	0.55	0.7	ns, max
G1/2 operand inputs to COUT output via AND	T _{GANDCY}	0.09	0.28	0.30	0.34	ns, max
Setup and Hold Times before/after Clock CLK						
CIN input to FFX	T _{CCKX} /T _{CKCX}	0.47 / 0	1.0 / 0	1.2 / 0	1.3 / 0	ns, min
CIN input to FFY	T _{CCKY} /T _{CKCY}	0.49 / 0	0.92 / 0	1.2 / 0	1.3 / 0	ns, min

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Table 1: BG560 BGA — XCV405E and XCV812E

Bank	Pin Description	Pin#
1	IO_L27N_YY	C14
1	IO_L27P_YY	D14
1	IO_L28N_Y	A13
1	IO_L28P_Y	E14
1	IO_L29N_YY	C13
1	IO_VREF_L29P_YY	D13 ¹
1	IO_L30N_YY	C12
1	IO_L30P_YY	E13
1	IO_L31N	A11
1	IO_L31P	D12
1	IO_L32N_YY	B11
1	IO_L32P_YY	C11
1	IO_L33N_YY	B10
1	IO_VREF_L33P_YY	D11
1	IO_L34N	C10
1	IO_L34P	A9
1	IO_L35N_YY	C9
1	IO_VREF_L35P_YY	D10 ¹
1	IO_L36N_YY	A8
1	IO_L36P_YY	B8
1	IO_L37N_Y	E10
1	IO_L37P_Y	C8
1	IO_L38N_YY	B7
1	IO_VREF_L38P_YY	A6
1	IO_L39N_YY	C7
1	IO_L39P_YY	D8
1	IO_L40N	A5
1	IO_L40P	B5
1	IO_L41N_YY	C6
1	IO_VREF_L41P_YY	D7
1	IO_L42N_YY	A4
1	IO_L42P_YY	B4
1	IO_L43N_Y	C5
1	IO_L43P_Y	E7
1	IO_WRITE_L44N_YY	D6
1	IO_CS_L44P_YY	A2

Table 1: BG560 BGA — XCV405E and XCV812E

Bank	Pin Description	Pin#
2	IO	D3
2	IO	F3
2	IO	G1
2	IO	J2
2	IO_DOUT_BUSY_L45P_YY	D4
2	IO_DIN_D0_L45N_YY	E4
2	IO_L46P_Y	F5
2	IO_L46N_Y	B3
2	IO_L47P	F4
2	IO_L47N	C1
2	IO_VREF_L48P_Y	G5
2	IO_L48N_Y	E3
2	IO_L49P_Y	D2
2	IO_L49N_Y	G4
2	IO_L50P_Y	H5
2	IO_L50N_Y	E2
2	IO_VREF_L51P_YY	H4
2	IO_L51N_YY	G3
2	IO_L52P_Y	J5
2	IO_L52N_Y	F1
2	IO_L53P	J4
2	IO_L53N	H3
2	IO_VREF_L54P_YY	K5 ¹
2	IO_L54N_YY	H2
2	IO_L55P_Y	J3
2	IO_L55N_Y	K4
2	IO_VREF_L56P_YY	L5
2	IO_D1_L56N_YY	K3
2	IO_D2_L57P_YY	L4
2	IO_L57N_YY	K2
2	IO_L58P_Y	M5
2	IO_L58N_Y	L3
2	IO_L59P	L1
2	IO_L59N	M4
2	IO_VREF_L60P_Y	N5 ¹
2	IO_L60N_Y	M2
2	IO_L61P_Y	N4

BG560 Differential Pin Pairs

Virtex-E Extended Memory devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package.

Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair is in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 2: BG560 Package Differential Pin Pair Summary XCV405E and XCV812E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
3	0	A17	C18	NA	IO LVDS 21
2	1	D17	E17	NA	IO LVDS 21
1	5	AJ17	AM18	NA	IO LVDS 115
0	4	AL17	AM17	NA	IO LVDS 115
IO LVDS Total Outputs: 183, Asynchronous Outputs: 79					
0	0	D29	E28	NA	-
1	0	A31	D28	√	-
2	0	C29	E27	√	VREF_0
3	0	D27	B30	1	-
4	0	B29	E26	√	-
5	0	C27	D26	√	VREF_0
6	0	A28	E25	NA	-
7	0	C26	D25	1	-
8	0	B26	E24	1	VREF_0
9	0	D24	C25	1	-
10	0	A25	E23	√	VREF_0
11	0	B24	D23	√	-
12	0	C23	E22	NA	-
13	0	D22	A23	√	-
14	0	B22	E21	√	VREF_0
15	0	C21	D21	1	-

Table 2: BG560 Package Differential Pin Pair Summary XCV405E and XCV812E

16	0	E20	B21	√	-
17	0	C20	D20	√	VREF_0
18	0	E19	B20	NA	-
19	0	C19	D19	1	-
20	0	D18	A19	1	VREF_0
21	1	E17	C18	NA	GCLK LVDS 3/2
22	1	B17	C17	1	-
23	1	D16	B16	1	VREF_1
24	1	C16	E16	1	-
25	1	C15	A15	NA	-
26	1	E15	D15	√	VREF_1
27	1	D14	C14	√	-
28	1	E14	A13	1	-
29	1	D13	C13	√	VREF_1
30	1	E13	C12	√	-
31	1	D12	A11	NA	-
32	1	C11	B11	√	-
33	1	D11	B10	√	VREF_1
34	1	A9	C10	2	-
35	1	D10	C9	1	VREF_1
36	1	B8	A8	1	-
37	1	C8	E10	NA	-
38	1	A6	B7	√	VREF_1
39	1	D8	C7	√	-
40	1	B5	A5	2	-
41	1	D7	C6	√	VREF_1
42	1	B4	A4	√	-
43	1	E7	C5	NA	-
44	1	A2	D6	√	CS
45	2	D4	E4	√	DIN_D0
46	2	F5	B3	2	-
47	2	F4	C1	NA	-
48	2	G5	E3	1	VREF_2
49	2	D2	G4	1	-

Table 2: BG560 Package Differential Pin Pair Summary
XCV405E and XCV812E

118	5	AK19	AM20	NA	-
119	5	AJ19	AL20	√	VREF_5
120	5	AN21	AL21	√	-
121	5	AJ20	AM22	1	-
122	5	AK21	AN23	√	VREF_5
123	5	AJ21	AM23	√	-
124	5	AK22	AM24	NA	-
125	5	AL23	AJ22	√	-
126	5	AK23	AL24	√	VREF_5
127	5	AN26	AJ23	2	-
128	5	AK24	AM26	1	VREF_5
129	5	AM27	AJ24	1	-
130	5	AL26	AK25	NA	-
131	5	AN29	AJ25	√	VREF_5
132	5	AK26	AM29	√	-
133	5	AM30	AJ26	2	-
134	5	AK27	AL29	√	VREF_5
135	5	AN31	AJ27	√	-
136	5	AM31	AK28	NA	-
137	6	AJ30	AH29	√	-
138	6	AH30	AK31	2	-
139	6	AJ31	AG29	NA	-
140	6	AG30	AK32	1	VREF_6
141	6	AF29	AH31	1	-
142	6	AF30	AH32	NA	-
143	6	AH33	AE29	√	VREF_6
144	6	AE30	AG33	2	-
145	6	AF32	AD29	NA	-
146	6	AD30	AE31	NA	VREF_6
147	6	AC29	AE32	NA	-
148	6	AC30	AD31	√	VREF_6
149	6	AC31	AB29	√	-
150	6	AB30	AC33	2	-
151	6	AA29	AB31	NA	-

Table 2: BG560 Package Differential Pin Pair Summary
XCV405E and XCV812E

152	6	AA31	AA30	1	VREF_6
153	6	Y29	AA32	1	-
154	6	Y30	AA33	NA	-
155	6	W29	Y32	√	VREF_6
156	6	W31	W30	2	-
157	6	V30	W33	NA	-
158	6	V31	V29	NA	VREF_6
159	6	U33	V32	NA	-
160	7	U32	U31	√	IRDY
161	7	T30	T32	NA	-
162	7	T31	T29	NA	VREF_7
163	7	R31	R33	NA	-
164	7	R29	R30	2	-
165	7	P31	P32	√	VREF_7
166	7	P29	P30	NA	-
167	7	N31	M32	1	-
168	7	L33	N30	1	VREF_7
169	7	L32	M31	NA	-
170	7	L31	M30	2	-
171	7	J33	M29	√	-
172	7	K31	L30	√	VREF_7
173	7	H33	L29	1	-
174	7	H32	J31	NA	VREF_7
175	7	H31	K29	NA	-
176	7	G32	J30	NA	-
177	7	G31	J29	√	VREF_7
178	7	E32	E33	NA	-
179	7	F31	H29	2	-
180	7	E31	D32	1	VREF_7
181	7	C33	G29	NA	-
182	7	D31	F30	NA	-

Notes:

1. AO in the XCV812E
2. AO in the XCV405E

Table 3: FG676 Fine-Pitch BGA — XCV405E

Bank	Pin Description	Pin #
NA	NC	B26
NA	NC	B24
NA	NC	B21
NA	NC	B16
NA	NC	B11
NA	NC	B1
NA	NC	AF25
NA	NC	AF24
NA	NC	AF2
NA	NC	AE6
NA	NC	AE3
NA	NC	AE26
NA	NC	AE24
NA	NC	AE21
NA	NC	AE16
NA	NC	AE14
NA	NC	AE11
NA	NC	AE1
NA	NC	AD25
NA	NC	AD2
NA	NC	AD1
NA	NC	AA6
NA	NC	AA25
NA	NC	AA21
NA	NC	AA2
NA	NC	A3
NA	NC	A25
NA	NC	A2
NA	NC	A15
NA	VCCINT	G7
NA	VCCINT	G20
NA	VCCINT	H8
NA	VCCINT	H19
NA	VCCINT	J9

Table 3: FG676 Fine-Pitch BGA — XCV405E

Bank	Pin Description	Pin #
NA	VCCINT	J10
NA	VCCINT	J11
NA	VCCINT	J16
NA	VCCINT	J17
NA	VCCINT	J18
NA	VCCINT	K9
NA	VCCINT	K18
NA	VCCINT	L9
NA	VCCINT	L18
NA	VCCINT	T9
NA	VCCINT	T18
NA	VCCINT	U9
NA	VCCINT	U18
NA	VCCINT	V9
NA	VCCINT	V10
NA	VCCINT	V11
NA	VCCINT	V16
NA	VCCINT	V17
NA	VCCINT	V18
NA	VCCINT	Y7
NA	VCCINT	Y20
NA	VCCINT	W8
NA	VCCINT	W19
0	VCCO	J13
0	VCCO	J12
0	VCCO	H9
0	VCCO	H12
0	VCCO	H11
0	VCCO	H10
1	VCCO	J15
1	VCCO	J14
1	VCCO	H18
1	VCCO	H17
1	VCCO	H16

Table 3: FG676 Fine-Pitch BGA — XCV405E

Bank	Pin Description	Pin #
1	VCCO	H15
2	VCCO	N18
2	VCCO	M19
2	VCCO	M18
2	VCCO	L19
2	VCCO	K19
2	VCCO	J19
3	VCCO	V19
3	VCCO	U19
3	VCCO	T19
3	VCCO	R19
3	VCCO	R18
3	VCCO	P18
4	VCCO	W18
4	VCCO	W17
4	VCCO	W16
4	VCCO	W15
4	VCCO	V15
4	VCCO	V14
5	VCCO	W9
5	VCCO	W12
5	VCCO	W11
5	VCCO	W10
5	VCCO	V13
5	VCCO	V12
6	VCCO	V8
6	VCCO	U8
6	VCCO	T8
6	VCCO	R9
6	VCCO	R8
6	VCCO	P9
7	VCCO	N9
7	VCCO	M9
7	VCCO	M8
7	VCCO	L8

Table 3: FG676 Fine-Pitch BGA — XCV405E

Bank	Pin Description	Pin #
7	VCCO	K8
7	VCCO	J8
NA	GND	V25
NA	GND	V2
NA	GND	U17
NA	GND	U16
NA	GND	U15
NA	GND	U14
NA	GND	U13
NA	GND	U12
NA	GND	U11
NA	GND	U10
NA	GND	T17
NA	GND	T16
NA	GND	T15
NA	GND	T14
NA	GND	T13
NA	GND	T12
NA	GND	T11
NA	GND	T10
NA	GND	R17
NA	GND	R16
NA	GND	R15
NA	GND	R14
NA	GND	R13
NA	GND	R12
NA	GND	R11
NA	GND	R10
NA	GND	P25
NA	GND	P17
NA	GND	P16
NA	GND	P15
NA	GND	P14
NA	GND	P13

Table 3: FG676 Fine-Pitch BGA — XCV405E

Bank	Pin Description	Pin #
NA	GND	P12
NA	GND	P11
NA	GND	P10
NA	GND	N2
NA	GND	N17
NA	GND	N16
NA	GND	N15
NA	GND	N14
NA	GND	N13
NA	GND	N12
NA	GND	N11
NA	GND	N10
NA	GND	M17
NA	GND	M16
NA	GND	M15
NA	GND	M14
NA	GND	M13
NA	GND	M12
NA	GND	M11
NA	GND	M10
NA	GND	L17
NA	GND	L16
NA	GND	L15
NA	GND	L14
NA	GND	L13
NA	GND	L12
NA	GND	L11
NA	GND	L10
NA	GND	K17
NA	GND	K16
NA	GND	K15
NA	GND	K14
NA	GND	K13
NA	GND	K12
NA	GND	K11

Table 3: FG676 Fine-Pitch BGA — XCV405E

Bank	Pin Description	Pin #
NA	GND	K10
NA	GND	J25
NA	GND	J2
NA	GND	E5
NA	GND	E22
NA	GND	D4
NA	GND	D23
NA	GND	C3
NA	GND	C24
NA	GND	B9
NA	GND	B25
NA	GND	B2
NA	GND	B18
NA	GND	B14
NA	GND	AF26
NA	GND	AF1
NA	GND	AE9
NA	GND	AE25
NA	GND	AE2
NA	GND	AE18
NA	GND	AE13
NA	GND	AD3
NA	GND	AD24
NA	GND	AC4
NA	GND	AC23
NA	GND	AB5
NA	GND	AB22
NA	GND	A26
NA	GND	A1

FG676 Differential Pin Pairs

Virtex-E Extended Memory devices have differential pin pairs that can also provide other functions when not used as a differential pair. A ✓ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package.

Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair is in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 4: FG676 Fine-Pitch BGA Differential Pin Pair Summary — XCV405E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
3	0	E13	B13	NA	IO_DLL_L21N
2	1	C13	F14	NA	IO_DLL_L21P
1	5	AB13	AF13	NA	IO_DLL_L115N
0	4	AA14	AC14	NA	IO_DLL_L115P
IOLVDS					
Total Pairs: 183, Asynchronous Output Pairs: 97					
0	0	F7	C4	NA	-
1	0	C5	G8	✓	-
2	0	E7	D6	✓	VREF
3	0	F8	A4	NA	-
4	0	D7	B5	NA	-
5	0	G9	E8	✓	VREF
6	0	F9	A5	✓	-
7	0	C7	D8	NA	-
8	0	E9	B7	NA	-
9	0	D9	A7	NA	-
10	0	G10	B8	NA	VREF
11	0	F10	C9	✓	-
12	0	E10	A8	NA	-
13	0	D10	G11	✓	-
14	0	F11	B10	✓	-
15	0	E11	C10	NA	-

Table 4: FG676 Fine-Pitch BGA Differential Pin Pair Summary — XCV405E

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	0	D11	G12	✓	-
17	0	F12	C11	✓	VREF
18	0	E12	A11	✓	-
19	0	C12	D12	NA	-
20	0	H13	A12	NA	VREF
21	1	F14	B13	NA	IO_LVDS_DLL
22	1	F13	E14	NA	-
23	1	A14	D14	NA	VREF
24	1	H14	C14	NA	-
25	1	C15	G14	✓	-
26	1	D15	E15	✓	VREF
27	1	F15	C16	✓	-
28	1	D16	G15	-	-
29	1	A17	E16	✓	-
30	1	E17	C17	✓	-
31	1	D17	F16	NA	-
32	1	C18	F17	✓	-
33	1	G16	A18	✓	VREF
34	1	G17	C19	✓	-
35	1	B19	D18	NA	-
36	1	E18	D19	NA	-
37	1	B20	F18	✓	-
38	1	C20	G19	✓	VREF
39	1	E19	G18	✓	-
40	1	D20	A21	✓	-
41	1	C21	F19	✓	VREF
42	1	E20	B22	✓	-
43	1	D21	A23	2	-
44	1	E21	C22	✓	CS
45	2	E23	F22	✓	DIN, D0
46	2	E24	F20	✓	-
47	2	G21	G22	2	-
48	2	F24	H20	1	VREF
49	2	E25	H21	1	-